



Welcome to **E-XFL.COM** 

# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

# **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2006
Number of Logic Elements/Cells	20060
Total RAM Bits	294912
Number of I/O	301
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	400-BGA
Supplier Device Package	400-FBGA (21x21)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1c20f400c6n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Section I–2 Altera Corporation



# 2. Cyclone Architecture

C51002-1.6

# Functional Description

Cyclone® devices contain a two-dimensional row- and column-based architecture to implement custom logic. Column and row interconnects of varying speeds provide signal interconnects between LABs and embedded memory blocks.

The logic array consists of LABs, with 10 LEs in each LAB. An LE is a small unit of logic providing efficient implementation of user logic functions. LABs are grouped into rows and columns across the device. Cyclone devices range between 2,910 to 20,060 LEs.

M4K RAM blocks are true dual-port memory blocks with 4K bits of memory plus parity (4,608 bits). These blocks provide dedicated true dual-port, simple dual-port, or single-port memory up to 36-bits wide at up to 250 MHz. These blocks are grouped into columns across the device in between certain LABs. Cyclone devices offer between 60 to 288 Kbits of embedded RAM.

Each Cyclone device I/O pin is fed by an I/O element (IOE) located at the ends of LAB rows and columns around the periphery of the device. I/O pins support various single-ended and differential I/O standards, such as the 66- and 33-MHz, 64- and 32-bit PCI standard and the LVDS I/O standard at up to 640 Mbps. Each IOE contains a bidirectional I/O buffer and three registers for registering input, output, and output-enable signals. Dual-purpose DQS, DQ, and DM pins along with delay chains (used to phase-align DDR signals) provide interface support with external memory devices such as DDR SDRAM, and FCRAM devices at up to 133 MHz (266 Mbps).

Cyclone devices provide a global clock network and up to two PLLs. The global clock network consists of eight global clock lines that drive throughout the entire device. The global clock network can provide clocks for all resources within the device, such as IOEs, LEs, and memory blocks. The global clock lines can also be used for control signals. Cyclone PLLs provide general-purpose clocking with clock multiplication and phase shifting as well as external outputs for high-speed differential I/O support.

Figure 2–1 shows a diagram of the Cyclone EP1C12 device.

functions. Another special packing mode allows the register output to feed back into the LUT of the same LE so that the register is packed with its own fan-out LUT. This provides another mechanism for improved fitting. The LE can also drive out registered and unregistered versions of the LUT output.

## **LUT Chain and Register Chain**

In addition to the three general routing outputs, the LEs within a LAB have LUT chain and register chain outputs. LUT chain connections allow LUTs within the same LAB to cascade together for wide input functions. Register chain outputs allow registers within the same LAB to cascade together. The register chain output allows a LAB to use LUTs for a single combinatorial function and the registers to be used for an unrelated shift register implementation. These resources speed up connections between LABs while saving local interconnect resources. "MultiTrack Interconnect" on page 2–12 for more information on LUT chain and register chain connections.

## addnsub Signal

The LE's dynamic adder/subtractor feature saves logic resources by using one set of LEs to implement both an adder and a subtractor. This feature is controlled by the LAB-wide control signal addnsub. The addnsub signal sets the LAB to perform either A + B or A -B. The LUT computes addition; subtraction is computed by adding the two's complement of the intended subtractor. The LAB-wide signal converts to two's complement by inverting the B bits within the LAB and setting carry-in = 1 to add one to the least significant bit (LSB). The LSB of an adder/subtractor must be placed in the first LE of the LAB, where the LAB-wide addnsub signal automatically sets the carry-in to 1. The Quartus II Compiler automatically places and uses the adder/subtractor feature when using adder/subtractor parameterized functions.

# **LE Operating Modes**

The Cyclone LE can operate in one of the following modes:

- Normal mode
- Dynamic arithmetic mode

Each mode uses LE resources differently. In each mode, eight available inputs to the LE—the four data inputs from the LAB local interconnect, carry-in0 and carry-in1 from the previous LE, the LAB carry-in from the previous carry-chain LAB, and the register chain connection—are directed to different destinations to implement the desired logic function. LAB-wide signals provide clock, asynchronous clear, asynchronous

# Embedded Memory

The Cyclone embedded memory consists of columns of M4K memory blocks. EP1C3 and EP1C6 devices have one column of M4K blocks, while EP1C12 and EP1C20 devices have two columns (refer to Table 1–1 on page 1–1 for total RAM bits per density). Each M4K block can implement various types of memory with or without parity, including true dual-port, simple dual-port, and single-port RAM, ROM, and FIFO buffers. The M4K blocks support the following features:

- 4,608 RAM bits
- 250 MHz performance
- True dual-port memory
- Simple dual-port memory
- Single-port memory
- Byte enable
- Parity bits
- Shift register
- FIFO buffer
- ROM
- Mixed clock mode

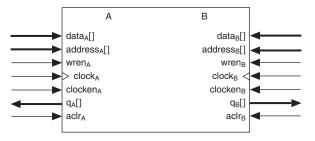


Violating the setup or hold time on the address registers could corrupt the memory contents. This applies to both read and write operations.

# **Memory Modes**

The M4K memory blocks include input registers that synchronize writes and output registers to pipeline designs and improve system performance. M4K blocks offer a true dual-port mode to support any combination of two-port operations: two reads, two writes, or one read and one write at two different clock frequencies. Figure 2–12 shows true dual-port memory.

Figure 2–12. True Dual-Port Memory Configuration



## **Byte Enables**

M4K blocks support byte writes when the write port has a data width of 16, 18, 32, or 36 bits. The byte enables allow the input data to be masked so the device can write to specific bytes. The unwritten bytes retain the previous written value. Table 2–5 summarizes the byte selection.

Table 2–5. Byte Enable for M4K Blocks Notes (1), (2)						
byteena[30] datain ×18 datain ×36						
[0] = 1	[80]	[80]				
[1] = 1	[179]	[179]				
[2] = 1	_	[2618]				
[3] = 1	_	[3527]				

Notes to Table 2-5:

- (1) Any combination of byte enables is possible.
- (2) Byte enables can be used in the same manner with 8-bit words, i.e., in ×16 and ×32 modes.

## **Control Signals and M4K Interface**

The M4K blocks allow for different clocks on their inputs and outputs. Either of the two clocks feeding the block can clock M4K block registers (renwe, address, byte enable, datain, and output registers). Only the output register can be bypassed. The six labclk signals or local interconnects can drive the control signals for the A and B ports of the M4K block. LEs can also control the clock\_a, clock\_b, renwe\_a, renwe\_b, clr\_a, clr\_b, clocken\_a, and clocken\_b signals, as shown in Figure 2–15.

The R4, C4, and direct link interconnects from adjacent LABs drive the M4K block local interconnect. The M4K blocks can communicate with LABs on either the left or right side through these row resources or with LAB columns on either the right or left with the column resources. Up to 10 direct link input connections to the M4K block are possible from the left adjacent LABs and another 10 possible from the right adjacent LAB. M4K block outputs can also connect to left and right LABs through 10 direct link interconnects each. Figure 2–16 shows the M4K block to logic array interface.

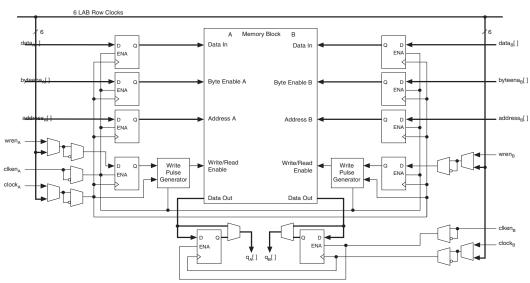


Figure 2–18. Input/Output Clock Mode in True Dual-Port Mode Notes (1), (2)

#### Notes to Figure 2–18:

- (1) All registers shown have asynchronous clear ports.
- (2) Violating the setup or hold time on the address registers could corrupt the memory contents. This applies to both read and write operations.

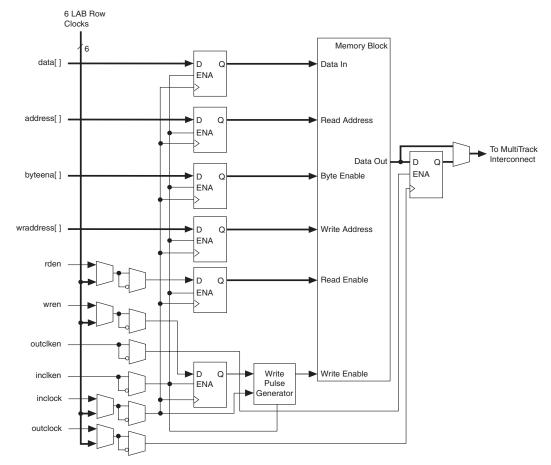


Figure 2–19. Input/Output Clock Mode in Simple Dual-Port Mode Notes (1), (2)

#### Notes to Figure 2-19:

- (1) All registers shown except the rden register have asynchronous clear ports.
- (2) Violating the setup or hold time on the address registers could corrupt the memory contents. This applies to both read and write operations.

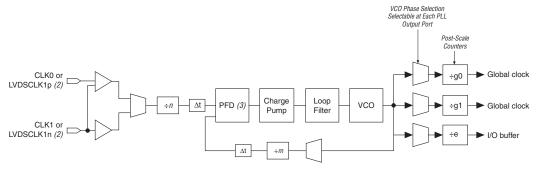
Table 2–6 shows the PLL features in Cyclone devices. Figure 2–25 shows a Cyclone PLL.

Table 2–6. Cyclone PLL Features						
Feature	PLL Support					
Clock multiplication and division	$m/(n \times post-scale counter)$ (1)					
Phase shift	Down to 125-ps increments (2), (3)					
Programmable duty cycle	Yes					
Number of internal clock outputs	2					
Number of external clock outputs	One differential or one single-ended (4)					

#### Notes to Table 2-6:

- (1) The *m* counter ranges from 2 to 32. The *n* counter and the post-scale counters range from 1 to 32.
- (2) The smallest phase shift is determined by the voltage-controlled oscillator (VCO) period divided by 8.
- (3) For degree increments, Cyclone devices can shift all output frequencies in increments of 45°. Smaller degree increments are possible depending on the frequency and divide parameters.
- (4) The EP1C3 device in the 100-pin TQFP package does not support external clock output. The EP1C6 device in the 144-pin TQFP package does not support external clock output from PLL2.

Figure 2–25. Cyclone PLL Note (1)



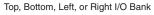
#### *Notes to Figure 2–25:*

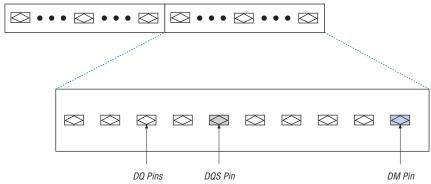
- The EP1C3 device in the 100-pin TQFP package does not support external outputs or LVDS inputs. The EP1C6 device in the 144-pin TQFP package does not support external output from PLL2.
- (2) LVDS input is supported via the secondary function of the dedicated clock pins. For PLL 1, the CLK0 pin's secondary function is LVDSCLK1p and the CLK1 pin's secondary function is LVDSCLK1n. For PLL 2, the CLK2 pin's secondary function is LVDSCLK2p and the CLK3 pin's secondary function is LVDSCLK2n.
- (3) PFD: phase frequency detector.

output pins (nSTATUS and CONF\_DONE) and all the JTAG pins in I/O bank 3 must operate at 2.5 V because the  $V_{CCIO}$  level of SSTL-2 is 2.5 V. I/O banks 1, 2, 3, and 4 support DQS signals with DQ bus modes of  $\times$  8.

For ×8 mode, there are up to eight groups of programmable DQS and DQ pins, I/O banks 1, 2, 3, and 4 each have two groups in the 324-pin and 400-pin FineLine BGA packages. Each group consists of one DQS pin, a set of eight DQ pins, and one DM pin (see Figure 2–33). Each DQS pin drives the set of eight DQ pins within that group.

Figure 2–33. Cyclone Device DQ and DQS Groups in ×8 Mode Note (1)





Note to Figure 2-33:

(1) Each DQ group consists of one DQS pin, eight DQ pins, and one DM pin.

Table 2–10 shows the number of DQ pin groups per device.

Table 2–10. DQ Pin Groups (Part 1 of 2)							
Device Package Number of × 8 DQ Total DQ Pin Pin Groups Count							
EP1C3	100-pin TQFP (1)	3	24				
	144-pin TQFP	4	32				
EP1C4	324-pin FineLine BGA	8	64				
	400-pin FineLine BGA	8	64				

of the standard. Using minimum settings provides signal slew rate control to reduce system noise and signal overshoot. Table 2–11 shows the possible settings for the I/O standards with drive strength control.

Table 2–11. Programmable Drive Strength Note (1)			
I/O Standard	I <sub>OH</sub> /I <sub>OL</sub> Current Strength Setting (mA)		
LVTTL (3.3 V)	4		
	8		
	12		
	16		
	24(2)		
LVCMOS (3.3 V)	2		
	4		
	8		
	12(2)		
LVTTL (2.5 V)	2		
.VTTL (2.5 V)	8		
	12		
	16(2)		
LVTTL (1.8 V)	2		
	8		
	12(2)		
LVCMOS (1.5 V)	2		
	4		
	8(2)		

#### *Notes to Table 2–11:*

- SSTL-3 class I and II, SSTL-2 class I and II, and 3.3-V PCI I/O Standards do not support programmable drive strength.
- (2) This is the default current strength setting in the Quartus II software.

# **Open-Drain Output**

Cyclone devices provide an optional open-drain (equivalent to an open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write-enable signals) that can be asserted by any of several devices.



Cyclone devices must be within the first 8 devices in a JTAG chain. All of these devices have the same JTAG controller. If any of the Cyclone devices are in the 9th or after they will fail configuration. This does not affect the SignalTap® II logic analyzer.



For more information on JTAG, refer to the following documents:

- AN 39: IEEE Std. 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices
- Jam Programming & Test Language Specification

# SignalTap II Embedded Logic Analyzer

Cyclone devices feature the SignalTap II embedded logic analyzer, which monitors design operation over a period of time through the IEEE Std. 1149.1 (JTAG) circuitry. A designer can analyze internal logic at speed without bringing internal signals to the I/O pins. This feature is particularly important for advanced packages, such as FineLine BGA packages, because it can be difficult to add a connection to a pin during the debugging process after a board is designed and manufactured.

# Configuration

The logic, circuitry, and interconnects in the Cyclone architecture are configured with CMOS SRAM elements. Altera FPGAs are reconfigurable and every device is tested with a high coverage production test program so the designer does not have to perform fault testing and can instead focus on simulation and design verification.

Cyclone devices are configured at system power-up with data stored in an Altera configuration device or provided by a system controller. The Cyclone device's optimized interface allows the device to act as controller in an active serial configuration scheme with the new low-cost serial configuration device. Cyclone devices can be configured in under 120 ms using serial data at 20 MHz. The serial configuration device can be programmed via the ByteBlaster II download cable, the Altera Programming Unit (APU), or third-party programmers.

In addition to the new low-cost serial configuration device, Altera offers in-system programmability (ISP)-capable configuration devices that can configure Cyclone devices via a serial data stream. The interface also enables microprocessors to treat Cyclone devices as memory and configure them by writing to a virtual memory location, making reconfiguration easy. After a Cyclone device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

Typically, the user-mode current during device operation is lower than the power-up current in Table 4–17. Altera recommends using the Cyclone Power Calculator, available on the Altera web site, to estimate the user-mode  $I_{\text{CCINT}}$  consumption and then select power supplies or regulators based on the higher value.

# **Timing Model**

The DirectDrive technology and MultiTrack interconnect ensure predictable performance, accurate simulation, and accurate timing analysis across all Cyclone device densities and speed grades. This section describes and specifies the performance, internal, external, and PLL timing specifications.

All specifications are representative of worst-case supply voltage and junction temperature conditions.

# **Preliminary and Final Timing**

Timing models can have either preliminary or final status. The Quartus® II software issues an informational message during the design compilation if the timing models are preliminary. Table 4–18 shows the status of the Cyclone device timing models.

Preliminary status means the timing model is subject to change. Initially, timing numbers are created using simulation results, process data, and other known parameters. These tests are used to make the preliminary numbers as close to the actual timing parameters as possible.

Final timing numbers are based on actual device operation and testing. These numbers reflect the actual performance of the device under worst-case voltage and junction temperature conditions.

Table 4–18. Cyclone Device Timing Model Status					
Device Preliminary Final					
EP1C3	_	✓			
EP1C4	_	✓			
EP1C6	_	✓			
EP1C12	_	✓			
EP1C20	_	✓			

### **Performance**

The maximum internal logic array clock tree frequency is limited to the specifications shown in Table 4–19.

Table 4–19.	Table 4–19. Clock Tree Maximum Performance Specification										
Parameter	Definition	-6 Speed Grade		-7 Speed Grade		-8 Speed Grade			Unito		
	Deminion	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Units
Clock tree f <sub>MAX</sub>	Maximum frequency that the clock tree can support for clocking registered logic		_	405	_	_	320		_	275	MHz

Table 4–20 shows the Cyclone device performance for some common designs. All performance values were obtained with the Quartus II software compilation of library of parameterized modules (LPM) functions or megafunctions. These performance values are based on EP1C6 devices in 144-pin TQFP packages.

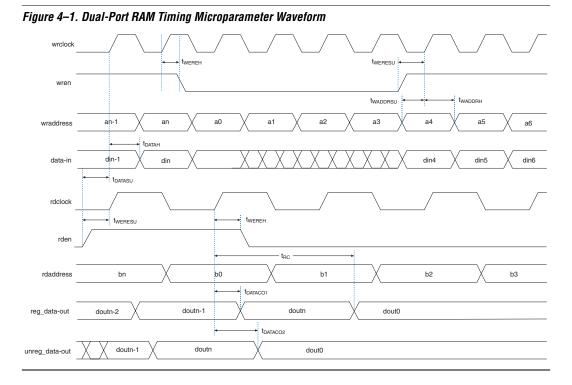
Table 4-20	Table 4–20. Cyclone Device Performance									
			R	esources U	sed	Performance				
Resource Used	Design Size and Function	Mode	LEs	M4K Memory Bits	M4K Memory Blocks	-6 Speed Grade (MHz)	-7 Speed Grade (MHz)	-8 Speed Grade (MHz)		
LE	16-to-1 multiplexer	_	21	_	_	405.00	320.00	275.00		
	32-to-1 multiplexer	_	44	_	_	317.36	284.98	260.15		
	16-bit counter	_	16	_	_	405.00	320.00	275.00		
	64-bit counter (1)	_	66	_	_	208.99	181.98	160.75		

Table 4–22. IOE Internal Timing Microparameter Descriptions				
Symbol	Parameter			
$t_{SU}$	IOE input and output register setup time before clock			
t <sub>H</sub>	IOE input and output register hold time after clock			
t <sub>CO</sub>	IOE input and output register clock-to-output delay			
t <sub>PIN2COMBOUT_R</sub>	Row input pin to IOE combinatorial output			
t <sub>PIN2COMBOUT_C</sub>	Column input pin to IOE combinatorial output			
t <sub>COMBIN2PIN_R</sub>	Row IOE data input to combinatorial output pin			
t <sub>COMBIN2PIN_C</sub>	Column IOE data input to combinatorial output pin			
t <sub>CLR</sub>	Minimum clear pulse width			
t <sub>PRE</sub>	Minimum preset pulse width			
t <sub>CLKHL</sub>	Minimum clock high or low time			

Table 4–23. M4	Table 4–23. M4K Block Internal Timing Microparameter Descriptions				
Symbol	Parameter				
t <sub>M4KRC</sub>	Synchronous read cycle time				
t <sub>M4KWC</sub>	Synchronous write cycle time				
t <sub>M4KWERESU</sub>	Write or read enable setup time before clock				
t <sub>M4KWEREH</sub>	Write or read enable hold time after clock				
t <sub>M4KBESU</sub>	Byte enable setup time before clock				
t <sub>M4KBEH</sub>	Byte enable hold time after clock				
t <sub>M4KDATAASU</sub>	A port data setup time before clock				
t <sub>M4KDATAAH</sub>	A port data hold time after clock				
t <sub>M4KADDRASU</sub>	A port address setup time before clock				
t <sub>M4KADDRAH</sub>	A port address hold time after clock				
t <sub>M4KDATABSU</sub>	B port data setup time before clock				
t <sub>M4KDATABH</sub>	B port data hold time after clock				
t <sub>M4KADDRBSU</sub>	B port address setup time before clock				
t <sub>M4KADDRBH</sub>	B port address hold time after clock				
t <sub>M4KDATACO1</sub>	Clock-to-output delay when using output registers				
t <sub>M4KDATACO2</sub>	Clock-to-output delay without output registers				
t <sub>M4KCLKHL</sub>	Minimum clock high or low time				
t <sub>M4KCLR</sub>	Minimum clear pulse width				

Table 4–24. Routing Delay Internal Timing Microparameter Descriptions					
Symbol Parameter					
t <sub>R4</sub>	Delay for an R4 line with average loading; covers a distance of four LAB columns				
t <sub>C4</sub>	Delay for an C4 line with average loading; covers a distance of four LAB rows				
t <sub>LOCAL</sub>	Local interconnect delay				

Figure 4–1 shows the memory waveforms for the M4K timing parameters shown in Table 4–23.



Symbol	-	6	-	7	-		
	Min	Max	Min	Max	Min	Max	Unit
t <sub>M4KRC</sub>	_	4,379		5,035		5,691	ps
t <sub>M4KWC</sub>	_	2,910		3,346		3,783	ps
t <sub>M4KWERESU</sub>	72	_	82	_	93	_	ps
t <sub>M4KWEREH</sub>	43	_	49	_	55	_	ps
t <sub>M4KBESU</sub>	72	_	82	_	93	_	ps
t <sub>M4KBEH</sub>	43	_	49	_	55	_	ps
t <sub>M4KDATAASU</sub>	72	_	82	_	93	_	ps
t <sub>M4KDATAAH</sub>	43	_	49	_	55	_	ps
t <sub>M4KADDRASU</sub>	72	_	82	_	93	_	ps
t <sub>M4KADDRAH</sub>	43	_	49	_	55	_	ps
t <sub>M4KDATABSU</sub>	72	_	82	_	93	_	ps
t <sub>M4KDATABH</sub>	43	_	49	_	55	_	ps
t <sub>M4KADDRBSU</sub>	72	_	82	_	93	_	ps
t <sub>M4KADDRBH</sub>	43	_	49	_	55	_	ps
t <sub>M4KDATACO1</sub>	_	621	_	714	_	807	ps
t <sub>M4KDATACO2</sub>	_	4,351	_	5,003	_	5,656	ps
t <sub>M4KCLKHL</sub>	1,234	_	1,562	_	1,818	_	ps
t <sub>M4KCLR</sub>	286	_	328		371		ps

Table 4–28. Routing Delay Internal Timing Microparameters							
Symbol	-	-6		-7		-8	
	Min	Max	Min	Max	Min	Max	Unit
t <sub>R4</sub>	_	261	_	300	_	339	ps
t <sub>C4</sub>	_	338	_	388	_	439	ps
t <sub>LOCAL</sub>	_	244	_	281	_	318	ps

# **External Timing Parameters**

External timing parameters are specified by device density and speed grade. Figure 4–2 shows the timing model for bidirectional IOE pin timing. All registers are within the IOE.

Table 4–51. Cyclone Maximum Output Clock Rate for Row Pins					
I/O Standard	-6 Speed -7 Speed Grade Grade		-8 Speed Grade	Unit	
LVTTL	296	285	273	MHz	
2.5 V	381	366	349	MHz	
1.8 V	286	277	267	MHz	
1.5 V	219	208	195	MHz	
LVCMOS	367	356	343	MHz	
SSTL-3 class I	169	166	162	MHz	
SSTL-3 class II	160	151	146	MHz	
SSTL-2 class I	160	151	142	MHz	
SSTL-2 class II	131	123	115	MHz	
3.3-V PCI (1)	66	66	66	MHz	
LVDS	320	303	275	MHz	

*Note to Tables 4–50 through 4–51:* 

# **PLL Timing**

Table 4–52 describes the Cyclone FPGA PLL specifications.

Table 4–52. Cyclone PLL Specifications (Part 1 of 2)					
Symbol	Symbol Parameter		Max	Unit	
f <sub>IN</sub>	Input frequency (-6 speed grade)	15.625	464	MHz	
	Input frequency (-7 speed grade)	15.625	428	MHz	
	Input frequency (-8 speed grade)	15.625	387	MHz	
f <sub>IN</sub> DUTY	Input clock duty cycle	40.00	60	%	
t <sub>IN</sub> JITTER	Input clock period jitter	_	± 200	ps	
f <sub>OUT_EXT</sub> (external PLL clock output)	PLL output frequency (-6 speed grade)	15.625	320	MHz	
	PLL output frequency (-7 speed grade)	15.625	320	MHz	
	PLL output frequency (-8 speed grade)	15.625	275	MHz	

<sup>(1)</sup> EP1C3 devices do not support the PCI I/O standard. These parameters are only available on row I/O pins.

Table 4–52. Cyclone PLL Specifications (Part 2 of 2)					
Symbol Parameter		Min	Max	Unit	
f <sub>OUT</sub> (to global clock)	PLL output frequency (-6 speed grade)	15.625	405	MHz	
	PLL output frequency (-7 speed grade)	15.625	320	MHz	
	PLL output frequency (-8 speed grade)	15.625	275	MHz	
t <sub>OUT</sub> DUTY	Duty cycle for external clock output (when set to 50%)	45.00	55	%	
t <sub>JITTER</sub> (1)	Period jitter for external clock output	_	±300 (2)	ps	
t <sub>LOCK</sub> (3)	Time required to lock from end of device configuration	10.00	100	μs	
f <sub>vco</sub>	PLL internal VCO operating range	500.00	1,000	MHz	
-	Minimum areset time	10	_	ns	
N, G0, G1, E	Counter values	1	32	integer	

#### Notes to Table 4-52:

- (1) The t<sub>JITTER</sub> specification for the PLL[2..1]\_OUT pins are dependent on the I/O pins in its V<sub>CCIO</sub> bank, how many of them are switching outputs, how much they toggle, and whether or not they use programmable current strength or slow slew rate.
- (2)  $f_{OUT} \ge 100$  MHz. When the PLL external clock output frequency ( $f_{OUT}$ ) is smaller than 100 MHz, the jitter specification is 60 mUI.
- (3)  $f_{IN/N}$  must be greater than 200 MHz to ensure correct lock detect circuit operation below -20 C. Otherwise, the PLL operates with the specified parameters under the specified conditions.

July 2003 v1.1	Updated timing information. Timing finalized for EP1C6 and EP1C20 devices. Updated performance information. Added PLL Timing section.	_
May 2003 v1.0	Added document to Cyclone Device Handbook.	_